

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
CONVEYING PARTY DATA																	
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jeng-Shien Hsieh</td> <td>03/04/2013</td> </tr> <tr> <td>Monsen Liu</td> <td>03/04/2013</td> </tr> <tr> <td>Chung-Hao Tsai</td> <td>03/04/2013</td> </tr> <tr> <td>Lai Wei Chih</td> <td>03/04/2013</td> </tr> <tr> <td>Yeh En-Hsiang</td> <td>03/04/2013</td> </tr> <tr> <td>Chuei-Tang Wang</td> <td>03/04/2013</td> </tr> <tr> <td>Chen-Hua Yu</td> <td>03/04/2013</td> </tr> </tbody> </table>		Name	Execution Date	Jeng-Shien Hsieh	03/04/2013	Monsen Liu	03/04/2013	Chung-Hao Tsai	03/04/2013	Lai Wei Chih	03/04/2013	Yeh En-Hsiang	03/04/2013	Chuei-Tang Wang	03/04/2013	Chen-Hua Yu	03/04/2013
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<table border="1"> <tr> <td>Name:</td> <td>Taiwan Semiconductor Manufacturing Company Limited</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Road 6</td> </tr> <tr> <td>Internal Address:</td> <td>Hsin-Chu Science Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Company Limited	Street Address:	No. 8, Li-Hsin Road 6	Internal Address:	Hsin-Chu Science Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77				
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CORRESPONDENCE DATA																	
<p>Fax Number: 2163733450 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 2166540090 Email: docketing@cooperlegalgroup.com Correspondent Name: Cooper Legal Group LLC Address Line 1: 6505 Rockside Road Suite 330 Address Line 4: Independence, OHIO 44131</p>																	
ATTORNEY DOCKET NUMBER:	TSMC 2012-1326																

PATENT

NAME OF SUBMITTER:

Daniel A. Tate

Total Attachments: 3

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ASSIGNMENT

For good and valuable consideration received of the hereinafter named assignee, receipt of which is hereby acknowledged, the undersigned

Jeng-Shien Hsieh Kaohsiung, TW	Monsen Liu Zhudong Township, TW	Chung-Hao Tsai Huatan Township, TW	Lai Wei Chih Hsinchu City, TW
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Yeh En-Hsiang Hsin-chu City, TW	Chuei-Tang Wang Taichung City, TW	Chen-Hua Yu Hsinchu City, TW
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NOW, THEREFORE, for and in consideration of our employment and the salary or wages paid to us by Taiwan Semiconductor Manufacturing Company Limited, I/we, Jeng-Shien Hsieh, Monsen Liu, Chung-Hao Tsai, Lai Wei Chih, Yeh En-Hsiang, Chuei-Tang Wang and Chen-Hua Yu, by these presents do sell, assign, and transfer unto said Taiwan Semiconductor Manufacturing Company Limited, a corporation organized and existing under the laws of the Republic of China, having its principal place of business at No. 8, Li-Hsin Road 6, Hsin-Chu Science Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring an interest therein, its successors and assigns, the entire right, title and interest, so far as concerns the United States and the Territories and Possessions thereof and all foreign countries, in and to the inventions entitled

RF CHOKE DEVICE FOR INTEGRATED CIRCUITS

for which application for United States Letters Patent has been filed on _____ under Serial No. _____, or was executed by the undersigned on the date below and is being filed concurrently herewith, said application for United States Letters Patent, any and all other applications for Letters Patent on said inventions in countries foreign to the United States, including all divisional, renewal, substitute, continuation and Convention applications based in whole or in part upon said inventions or upon said applications, and any and all Letters Patent and reissues and extensions of Letters Patent granted for said inventions or upon said applications, and every priority right that is or may be predicated upon or arise from said inventions, said applications and said Letters Patent; said assignee being hereby authorized to file patent applications in any or all countries on any or all said inventions in the name of the undersigned or in the name of said assignee or otherwise as said assignee may deem advisable, under the International Convention or otherwise; the Commissioner of Patents and Trademarks of the United States of America and the empowered officials of all other governments being hereby authorized to issue or transfer all said Letters Patent to said assignee in accordance herewith; this assignment being under covenant, not only that full power to make the same is had by the undersigned, but also that such assigned right is not encumbered by any grant, license, or other right heretofore given, and that the undersigned will do all acts reasonably serving to assure that said inventions, patent applications and Letters Patent shall be held and enjoyed by said assignee as fully and entirely as the same could have been held and enjoyed by the undersigned if this assignment had not been made, and particularly to execute and deliver to said assignee all lawful documents including

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petitions, specifications, oaths, assignments, invention disclaimers, and lawful affidavits in form and substance which may be requested by said assignee, to furnish said assignee with all facts relating to said inventions or the history thereof and any and all documents, photographs, models, samples or other physical exhibits which may be useful for establishing the facts of conception, disclosure and reduction to practice of said inventions, and to testify in any proceedings relating to said inventions, patent applications and Letters Patent.

<u>Jeng-Shien Hsieh</u>	<u>03/04/2013</u>
Inventor's Signature	Date
<u>Jeng-Shien Hsieh</u>	
Printed Name in English	

<u>Monsen Liu</u>	<u>03/04/2013</u>
Inventor's Signature	Date
<u>Monsen Liu</u>	
Printed Name in English	

<u>Chung-Hao Tsai</u>	<u>03/04/2013</u>
Inventor's Signature	Date
<u>Chung-Hao Tsai</u>	
Printed Name in English	

<u>Lai Wei Chih</u>	<u>03/04/2013</u>
Inventor's Signature	Date
<u>Lai Wei Chih</u>	
Printed Name in English	

<u>Yeh En-Hsiang</u>	<u>03/04/2013</u>
Inventor's Signature	Date
<u>Yeh En-Hsiang</u>	
Printed Name in English	

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<u>Chuei-Tang Wang</u>	<u>03/04/2013</u>
Inventor's Signature	Date
<u>Chuei-Tang Wang</u>	
Printed Name in English	

<u>Y</u>	<u>3/4/13</u>
Inventor's Signature	Date
<u>Chen-Hua Yu</u>	
Printed Name in English	